

OMB No. 6514-0011(exp-4/94)

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To the Honorable Commissione.

the attached original Documents or copy thereof

1. Name of conveying party(ies):

Hiroshi ITOH

9-28-00

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: Nippon Shokubai Co., Ltd.

Internal Address:

Street Address: 1-1, Koraibashi 4-chome,
Chuo-ku, Osaka-shi
Osaka 541-0043 Japan

City: State: ZIP:

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: September 20, 2000

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

September 20, 2000

A. Patent Application No.(s)

B. Patent No.(s)

Additional Application numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Garrett V. Davis

Roylance, Abrams, Berdo & Goodman, LLP

Internal Address:

Street Address: 1300 19th Street, N.W.
Suite 600

City: Washington State: D.C. ZIP: 20036

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) : \$40.00

☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Garrett V. Davis

Name of Person Signing

Signature

Sept 20, 2000

Date

Total number of pages including cover sheet, attachments, and document:

3

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

ASSIGNMENT

WHEREAS, I, Hiroshi ITOH, citizen of JAPAN, residing at Kobe-shi, HYOGO JAPAN (hereinafter ASSIGNOR), have made a certain invention entitled BIODEGRADABLE POLYESTER RESIN COMPOSITION AND ITS USE for which I am making application for Letters Patent of the United States, which application has been executed concurrently herewith; and

WHEREAS, Nippon Shokubai Co., Ltd., a corporation duly organized under the laws of JAPAN, located and doing business at 1-1, Koraibashi 4-chome, Chuo-ku, Osaka-shi, Osaka 541-0043 JAPAN (hereinafter ASSIGNEE), is desirous of acquiring the entire right, title and interest in and to the aforementioned invention and the aforementioned application and any and all Letters Patent to be obtained on said invention and/or application;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

BE IT KNOWN that for good and valuable consideration paid to me by said ASSIGNEE, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, by these presents do hereby sell, assign, set over and transfer unto the said ASSIGNEE, its successors, legal representatives or assigns, the entire right, title and interest in and to the aforesaid invention in and for the United States and all countries foreign thereto; and in, to and under the aforesaid United States application and any corresponding foreign applications and any divisional, continuing, substitute or reissue applications or supplementary disclosures which may be filed on said invention in any country; and our right to file said foreign applications and claim priority under the provisions of the International Convention; and any Letters Patent of the United States or any foreign country issued or granted on said invention and/or said applications;

AND I HEREBY authorize and request the Patent Office or other issuing authority to issue any and all patents on said invention and/or said application to said ASSIGNEE as sole assignee; and I further hereby authorize said ASSIGNEE to file and prosecute any of said foreign applications in its own name;

AND I HEREBY covenant that I have the full right to convey the entire right, title and interest herein assigned and that I have not executed and will not execute any assignment or other instrument in conflict herewith;

AND I HEREBY further covenant and agree to communicate to said ASSIGNEE, or its legal representatives, successors or assigns, any facts relating to said invention, including evidence for interference purposes or other proceedings, whenever requested, and to testify in any interference or in any other legal proceeding, when requested, and to execute and deliver on request all lawful papers required to make any of the foregoing provisions effective; and to perform the aforesaid communicating, executing and delivering, without any payment except expenses and to perform the aforesaid testifying for reasonable compensation; and generally to do everything possible to aid the said ASSIGNEE, its successors, legal representatives or assigns to obtain and enforce proper patent protection on and for said invention in all countries, and likewise I make these provisions binding upon our heirs, legal representatives and/or administrators.

IN WITNESS WHEREOF, I have hereunder set my hand and seal.

September 20, 2000

Date

Hiroshi Itoh

Name: Hiroshi ITOH